



Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Test Conditions		SJxx40xA	SJxx40x2A	Unit
I_{GT}	$V_D = 12\text{V}; R_L = 30\ \Omega$	MAX.	40	15	mA
		MIN.	5	3	
V_{GT}		MAX.	1.5		V
dv/dt	$V_D = V_{DRM}; \text{gate open}; T_J = 125^\circ\text{C}$	400V	650	400	V/ μs
		600V	600	350	
	$V_D = V_{DRM}; \text{gate open}; T_J = 150^\circ\text{C}$	400V	550	-	
		600V	500	-	
	$V_D = 67\%V_{DRM}; \text{gate open}; T_J = 150^\circ\text{C}$	400V	-	300	
		600V	-	250	
V_{GD}	$V_D = V_{DRM}; R_L = 3.3\ \text{k}\Omega; T_J = 150^\circ\text{C}$	MIN.	0.2		V
I_H	$I_T = 400\text{mA}$ (initial)	MAX.	60	50	mA
t_q	$I_T = 2\text{A}; t_p = 50\mu\text{s}; dv/dt = 5\text{V}/\mu\text{s}; di/dt = -30\text{A}/\mu\text{s}$	MAX.	35		μs
t_{gt}	$I_G = 2 \times I_{GT}; PW = 15\mu\text{s}; I_T = 80\text{A}$	TYP.	2		μs

Note: xx=voltage/10, x=package

Static Characteristics

Symbol	Test Conditions		Value	Unit	
V _{TM}	I _T = 80A; t _p = 380μs		MAX.	1.7	V
I _{DRM} / I _{RRM}	@ V _{DRM} / V _{RRM}	T _J = 25°C	MAX.	10	μA
		T _J = 125°C		2000	
		T _J = 150°C		4000	

Thermal Resistances

Symbol	Parameter		Value	Unit
$R_{\theta(JC)}$	Junction to case (AC)	SJxx40LxA	1.9	$^\circ\text{C}/\text{W}$
		SJxx40RxA/SJxx40Nx A	0.8	$^\circ\text{C}/\text{W}$

Note: xx = voltage, x = sensitivity & type

Figure 1: Normalized DC Gate Trigger Current vs. Junction Temperature

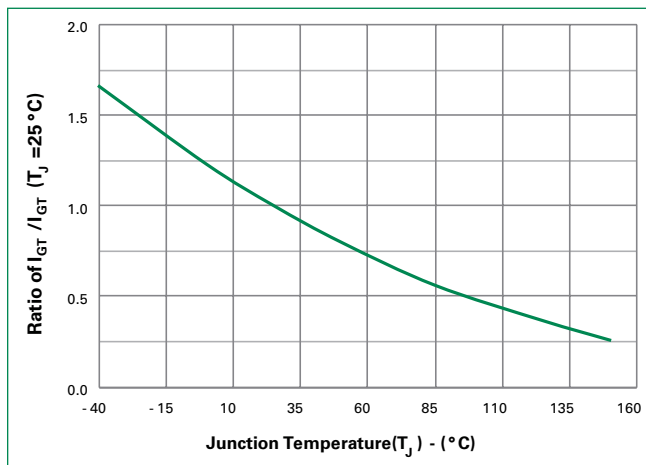


Figure 2: Normalized DC Gate Trigger Voltage vs. Junction Temperature

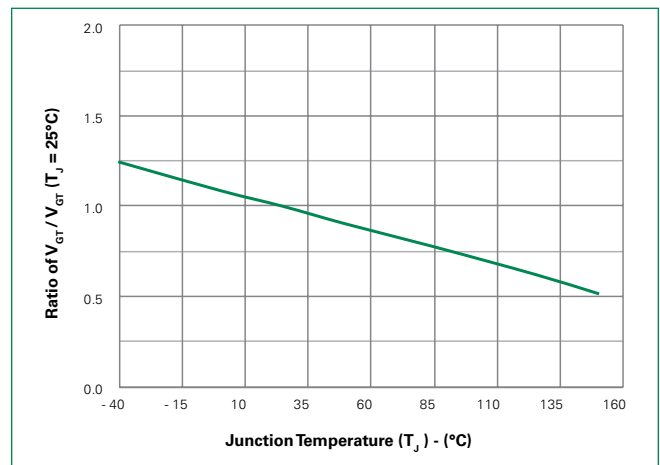




Figure 3: Normalized DC Holding Current vs. Junction Temperature

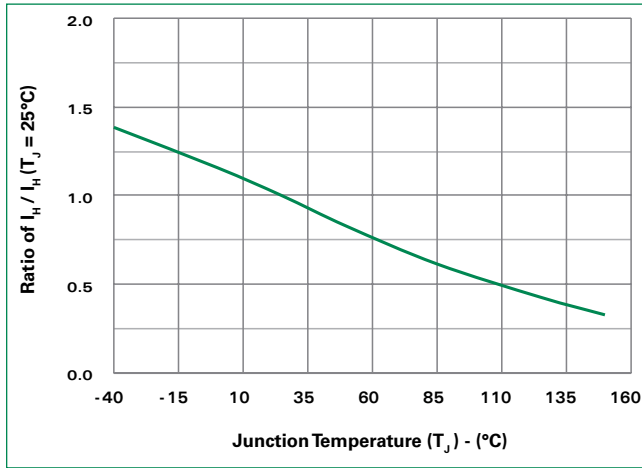


Figure 4: On-State Current vs. On-State Voltage (Typical)

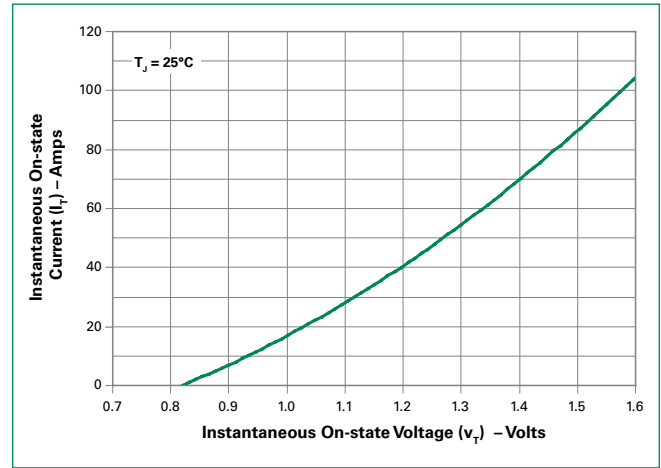


Figure 5: Power Dissipation (Typical) vs. RMS On-State Current

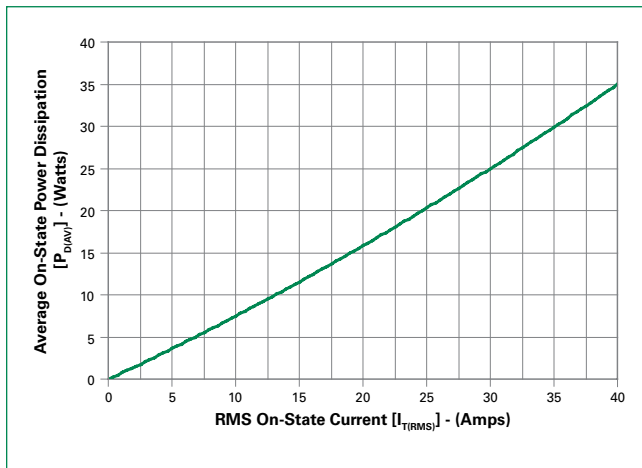


Figure 6: Maximum Allowable Case Temperature vs. RMS On-State Current

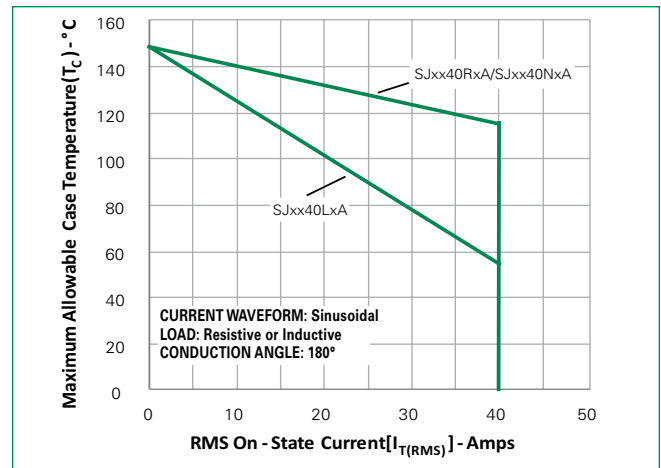


Figure 7: Maximum Allowable Case Temperature vs. Average On-State Current

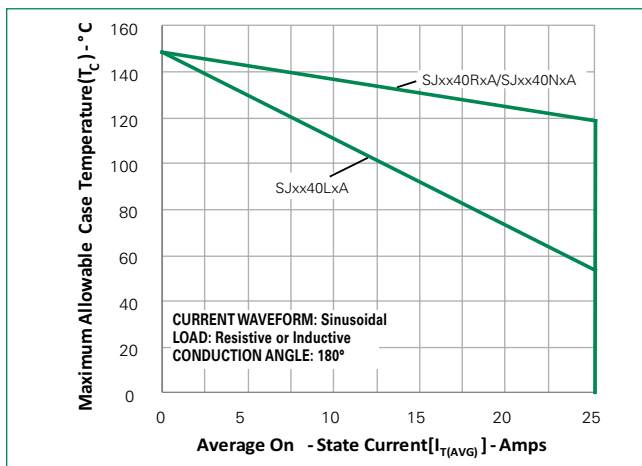


Figure 8: Peak Capacitor Discharge Current

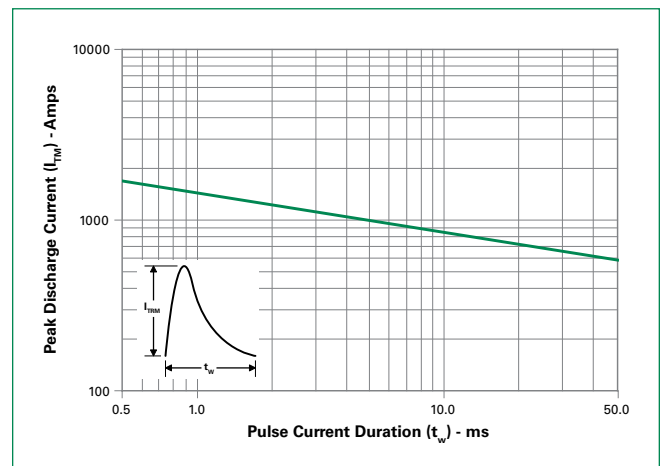




Figure 9: Peak Capacitor Discharge Current Derating

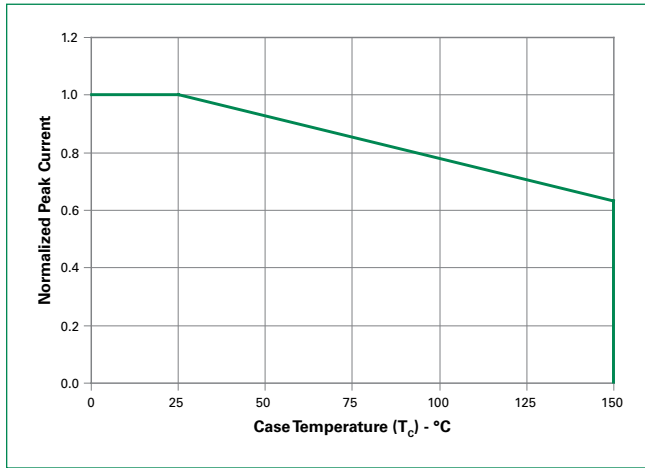
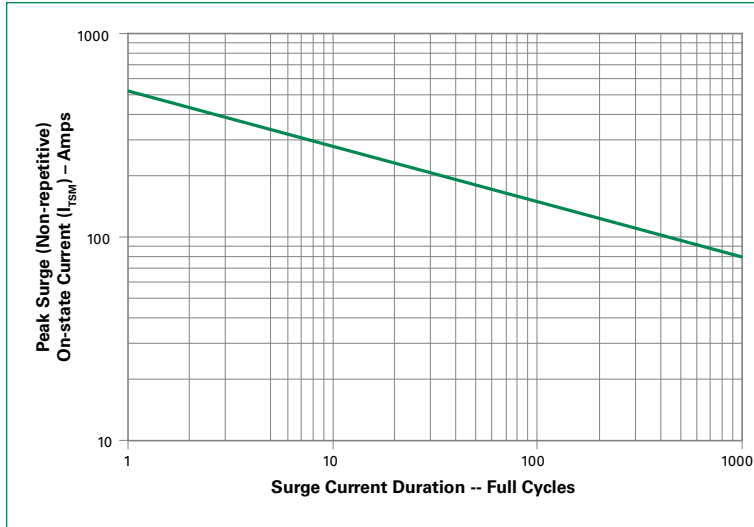


Figure 10: Surge Peak On-State Current vs. Number of Cycles



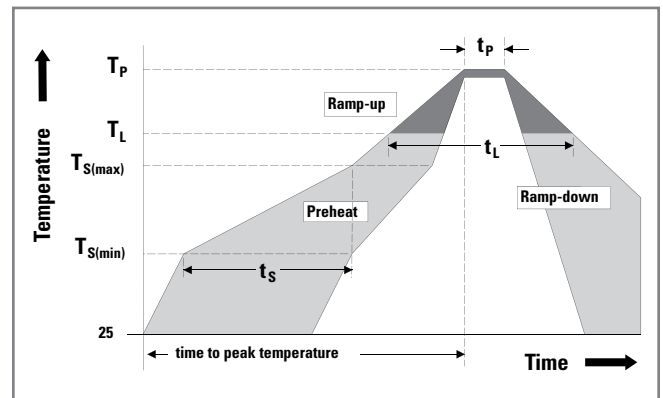
SUPPLY FREQUENCY: 60 Hz Sinusoidal
LOAD: Resistive
RMS On-State Current [$I_{T(RMS)}$]: Maximum Rated Value at Specified Case Temperature

Notes:

1. Gate control may be lost during and immediately following surge current interval.
2. Overload may not be repeated until junction temperature has returned to steady-state rated value.

Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		5°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Time (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		280°C



Physical Specifications

Terminal Finish	100% Matte Tin-plated
Body Material	UL Recognized compound meeting flammability rating V-0
Lead Material	Copper Alloy

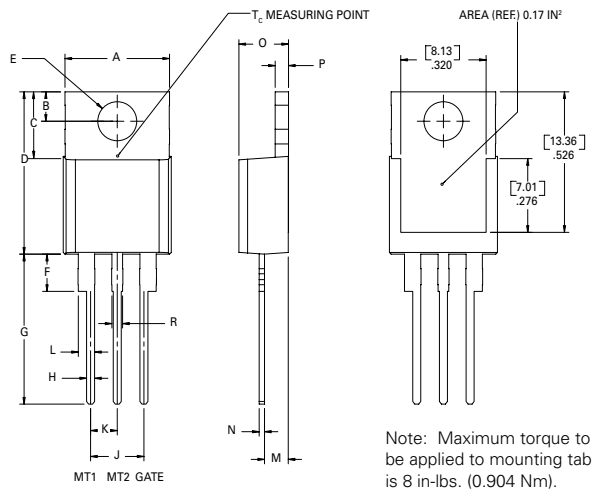
Design Considerations

Careful selection of the correct component for the application's operating parameters and environment will go a long way toward extending the operating life of the Thyristor. Good design practice should limit the maximum continuous current through the main terminals to 75% of the component rating. Other ways to ensure long life for a power discrete semiconductor are proper heat sinking and selection of voltage ratings for worst case conditions. Overheating, overvoltage (including dv/dt), and surge currents are the main killers of semiconductors. Correct mounting, soldering, and forming of the leads also help protect against component damage.

Environmental Specifications

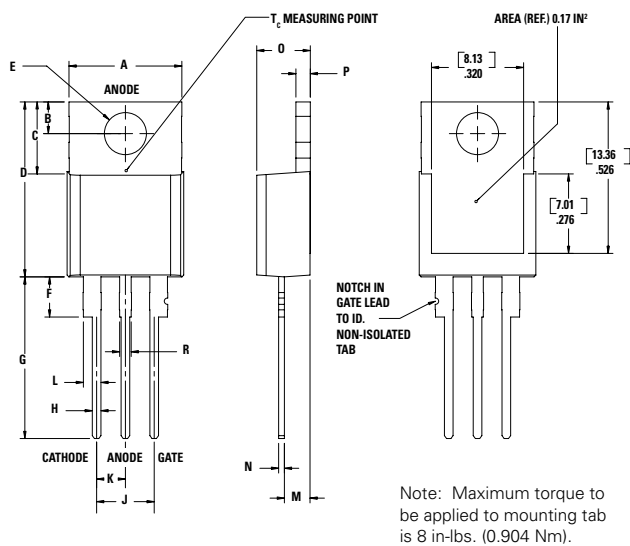
Test	Specifications and Conditions
AC Blocking	MIL-STD-750, M-1040, Cond A Applied Peak AC voltage @ 150°C for 1008 hours
Temperature Cycling	MIL-STD-750, M-1051, 1000 cycles; 55°C to +150°C; 15-min dwell-time
Temperature/Humidity	EIA / JEDEC, JESD22-A101 1008 hours; 160VDC - DC: 85°C; 85% rel humidity
Resistance to Solder Heat	MIL-STD-750 Method 2031
Solderability	ANSI/J-STD-002, category 3, Test A
Lead Bend	MIL-STD-750, M-2036 Cond E
Moisture Sensitivity Level	Level 1, JEDEC-J-STD-020D
UHAIST	JESD22A-118, 96 hrs, 130°C / 85% RH
IOL	MIL-STD-750 Method 1037

Dimensions — TO-220AB (L Package) — Isolated Mounting Tab



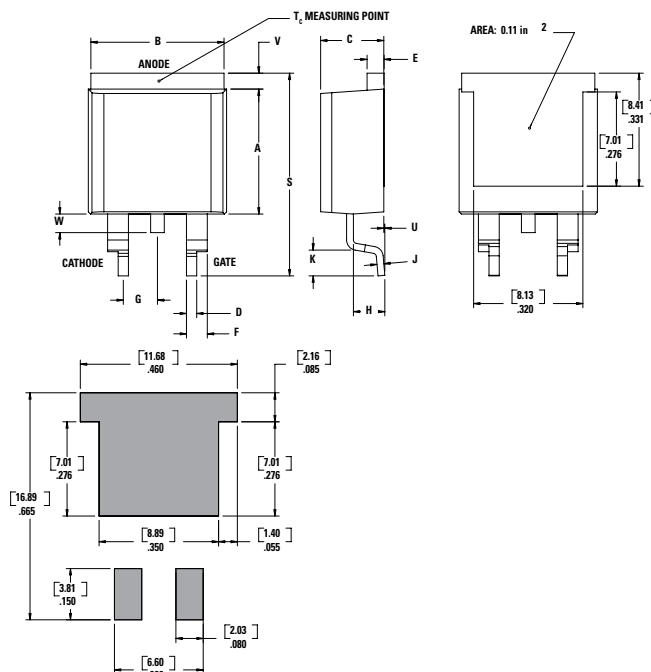
Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.380	0.420	9.65	10.67
B	0.105	0.115	2.66	2.92
C	0.230	0.250	5.85	6.35
D	0.590	0.620	14.98	15.75
E	0.142	0.147	3.61	3.73
F	0.110	0.130	2.80	3.30
G	0.540	0.575	13.71	14.60
H	0.025	0.035	0.63	0.89
J	0.195	0.205	4.95	5.21
K	0.095	0.105	2.41	2.67
L	0.060	0.075	1.52	1.91
M	0.085	0.095	1.78	2.16
N	0.018	0.024	0.45	0.61
O	0.178	0.188	4.52	4.78
P	0.045	0.060	1.14	1.53
R	0.038	0.048	0.97	1.22

Dimensions — TO-220AB (R-Package) — Non-Isolated Mounting Tab Common with Center Lead



Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.380	0.420	9.65	10.67
B	0.105	0.115	2.67	2.92
C	0.230	0.250	5.84	6.35
D	0.590	0.620	14.99	15.75
E	0.142	0.147	3.61	3.73
F	0.110	0.130	2.79	3.30
G	0.540	0.575	13.72	14.61
H	0.025	0.035	0.64	0.89
J	0.195	0.205	4.95	5.21
K	0.095	0.105	2.41	2.67
L	0.060	0.075	1.52	1.91
M	0.085	0.095	2.16	2.41
N	0.018	0.024	0.46	0.61
O	0.178	0.188	4.52	4.78
P	0.045	0.060	1.14	1.52
R	0.038	0.048	0.97	1.22

Dimensions — TO- 263 (N-package) — D²-Pak Surface Mount



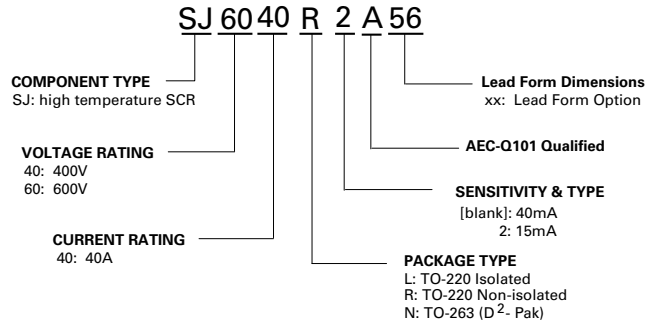
Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.360	0.370	9.14	9.40
B	0.380	0.420	9.65	10.67
C	0.178	0.188	4.52	4.78
D	0.025	0.035	0.63	0.89
E	0.048	0.055	1.22	1.40
F	0.060	0.075	1.52	1.91
G	0.095	0.105	2.41	2.67
H	0.083	0.093	2.11	2.36
J	0.018	0.024	0.46	0.61
K	0.090	0.110	2.29	2.79
S	0.590	0.625	14.99	15.87
V	0.035	0.045	0.89	1.14
U	0.002	0.010	0.05	0.25
W	0.040	0.070	1.02	1.78



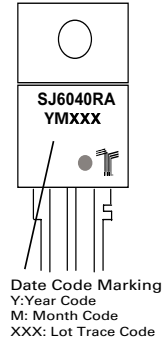
Thyristors

40 Amp Standard High Temperature SCRs

Part Numbering System



Part Marking System



Product Selector

Part Number	Voltage		Gate Sensitivity	Type	Package
	400V	600V			
SJxx40LA	X	X	40mA	Standard SCR	TO-220L
SJxx40RA	X	X	40mA	Standard SCR	TO-220R
SJxx40NA	X	X	40mA	Standard SCR	TO-263
SJxx40L2A	X	X	15mA	Standard SCR	TO-220L
SJxx40R2A	X	X	15mA	Standard SCR	TO-220R
SJxx40N2A	X	X	15mA	Standard SCR	TO-263

Note: xx = Voltage

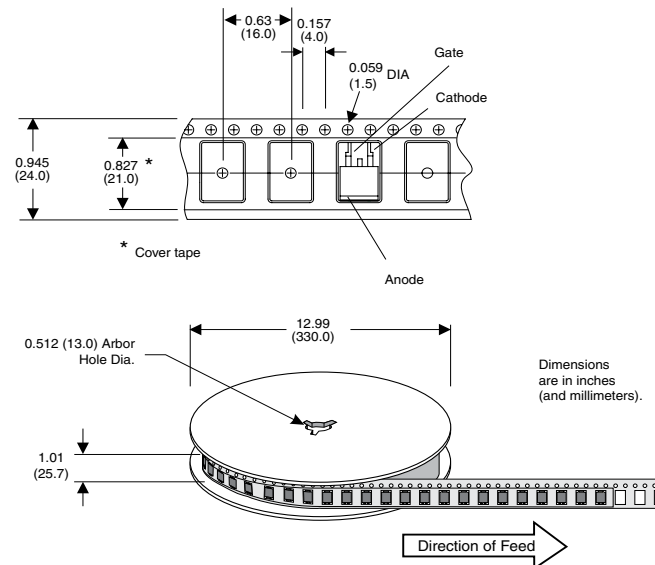
Packing Options

Part Number	Marking	Weight	Packing Mode	Base Quantity
SJxx40LATP	SJxx40LA	2.2g	Tube	1000 (50 per tube)
SJxx40RATP	SJxx40RA	2.2g	Tube	1000 (50 per tube)
SJxx40NATP	SJxx40NA	1.6g	Tube	1000 (50 per tube)
SJxx40NARP	SJxx40NA	1.6g	Embossed Carrier	500
SJxx40L2ATP	SJxx40L2A	2.2g	Tube	1000 (50 per tube)
SJxx40R2ATP	SJxx40R2A	2.2g	Tube	1000 (50 per tube)
SJxx40N2ATP	SJxx40N2A	1.6g	Tube	1000 (50 per tube)
SJxx40N2ARP	SJxx40N2A	1.6g	Embossed Carrier	500

Note: xx = Voltage



Reel Pack (RP) for TO-263 Embossed Carrier Specifications



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